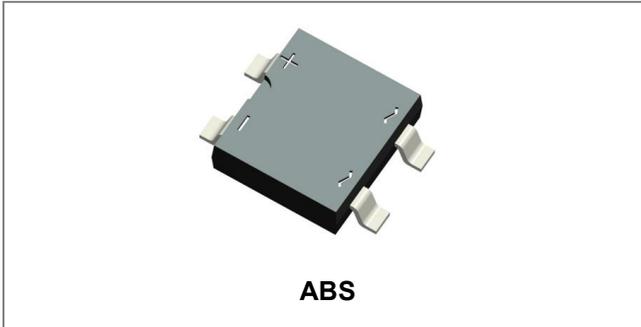


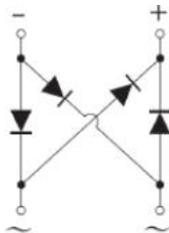
**ABS22 THRU ABS210
SINGLE PHASE 2.0A MP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER**



Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: SOPA-4, Molded plastic ABS
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting Position: Any

Maximum Ratings@T_A=25°C unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

Type Number	Symbol	ABS22	ABS24	ABS26	ABS28	ABS210	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{DC}	200	400	600	800	1000	V
RMS Reverse Voltage	V _{RMS}	140	280	420	560	700	V
Average Rectified Output Current @T _C =100°C	I _o	2.0					A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	60					A
I ² t Rating for Fusing (t < 8.3ms)	I ² t	15					A ² s

Electrical Characteristics:

Type Number	Symbol	ABS22	ABS24	ABS26	ABS28	ABS210	Unit
Forward Voltage (per element) @ $I_F = 1.0A$ @ $I_F = 2.0A$	V_F			0.95 1.00			V
Peak Reverse Current @ $T_A = 25^\circ C$ At Rated DC Blocking Voltage @ $T_A = 125^\circ C$	I_R			5.0 200			μA

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

Type Number	Symbol	ABS22	ABS24	ABS26	ABS28	ABS210	Unit
Typical Thermal Resistance (per leg)	$R_{\theta JA}$ $R_{\theta JL}$			62.5 25			$^\circ C/W$
Operating and Storage Temperature Range	T_J, T_{STG}			-55 to +150			$^\circ C$

Ratings and Characteristics Curves

FIG.1 FORWARD CURRENT DERATING CURVE

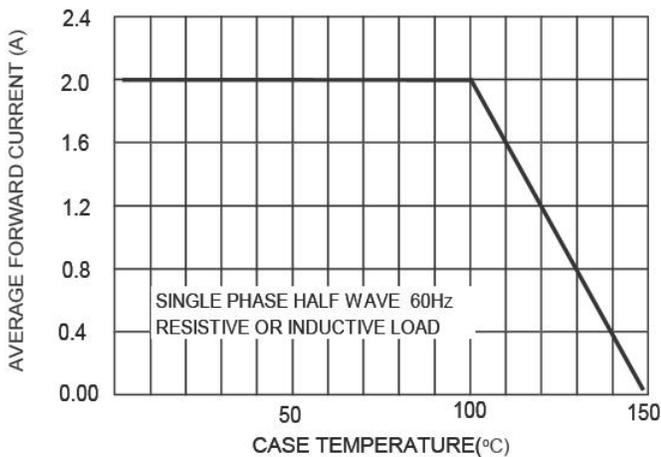


FIG.2 TYPICAL FORWARD CHARACTERISTICS

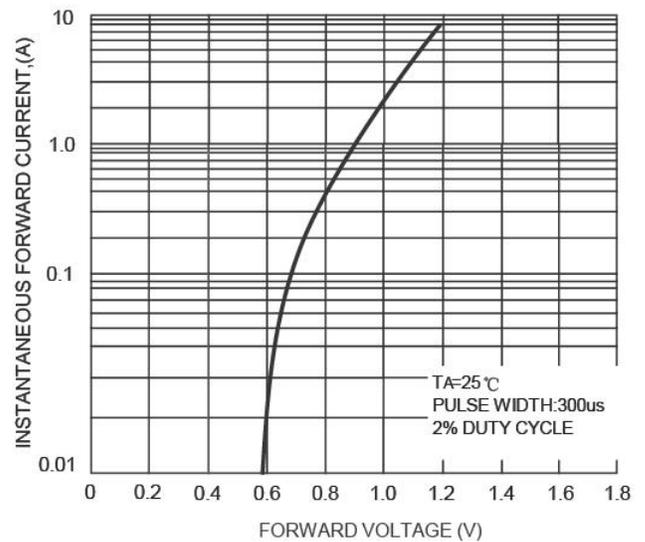


FIG.3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

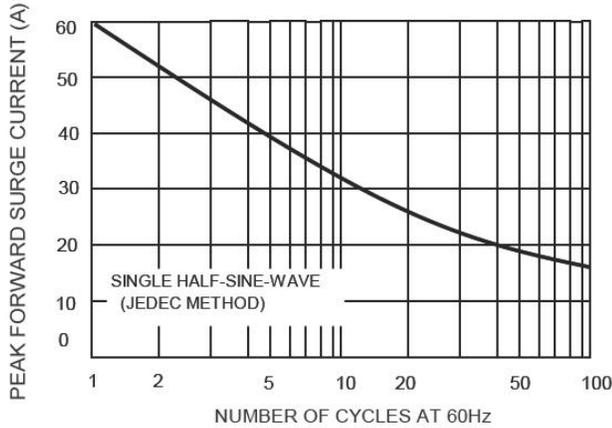
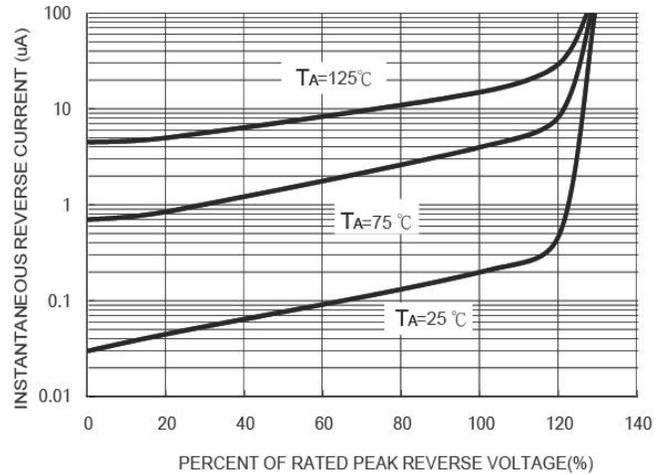
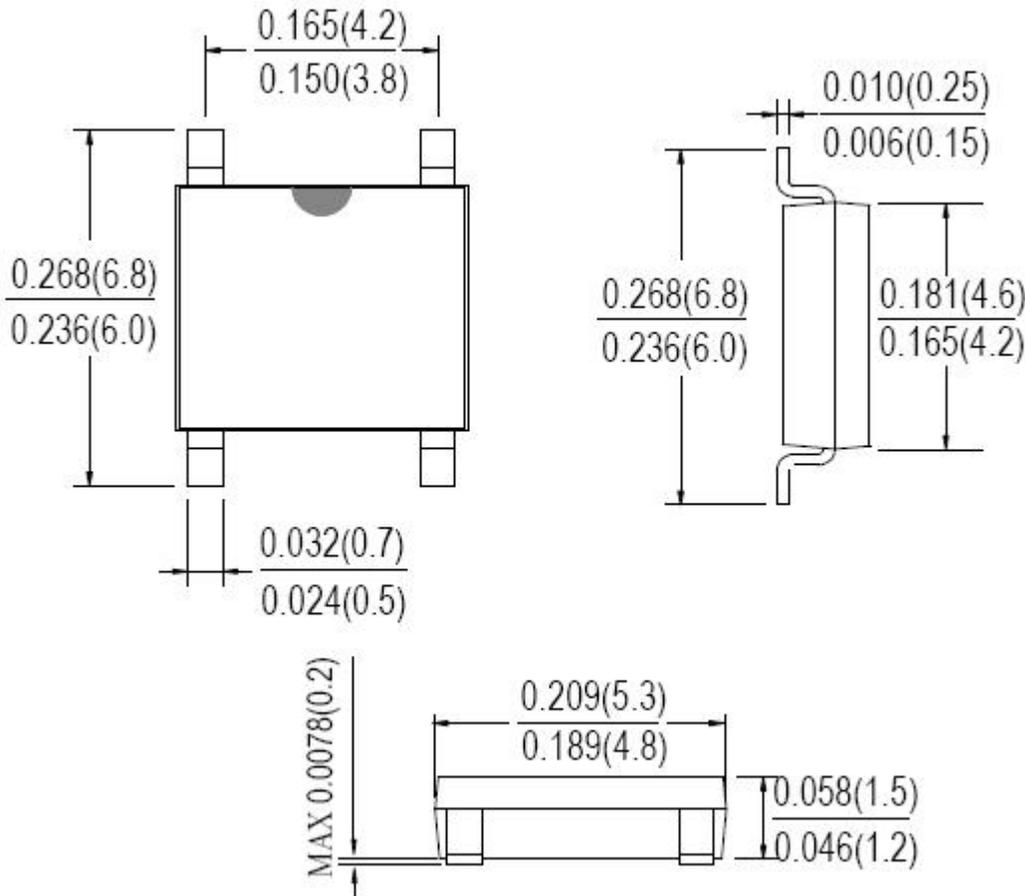


FIG. 4 TYPICAL REVERSE CHARACTERISTICS



Mechanical Dimensions ABS(Inches/Millimeters)



Ordering Information

Device	Package	Shipping
ABS22 THRU ABS210	ABS (Pb-Free)	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

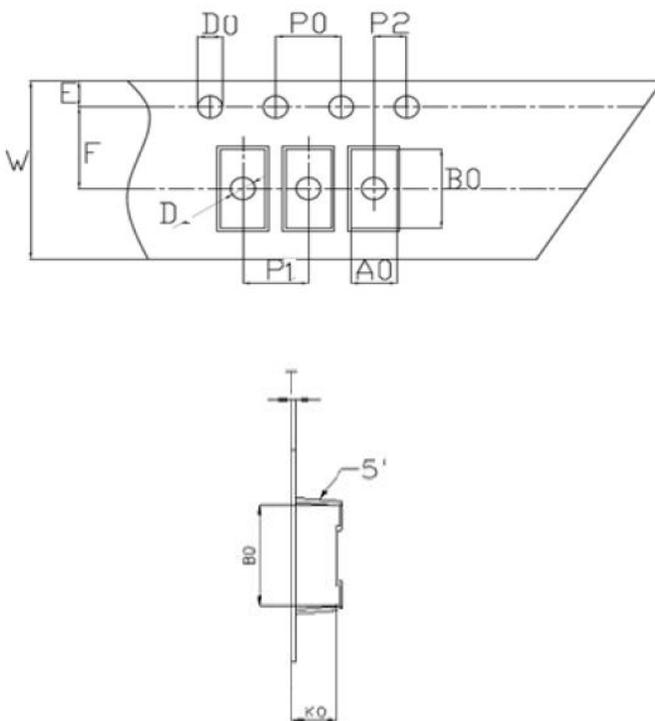


Where XXXXX is YYWWL

ABS22 = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape & Reel Specification ABS



SYMBOL	Millimeters	
	Min.	Max.
A0	5.21	5.41
B0	7.10	7.30
D0	1.50	1.60
D1	1.40	1.60
P0	3.90	4.10
P1	7.90	8.10
P2	1.95	2.05
E	1.65	1.85
K0	1.55	1.75
F	5.45	5.55
W	11.90	12.10
T	0.24	0.30
10P0	39.80	40.20

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